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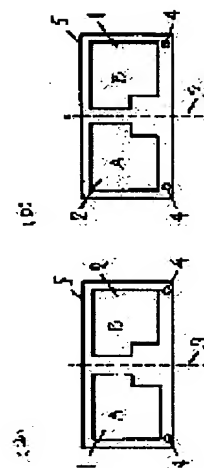
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(54) MULTIPLY BEVELED SUBSTRATE

(57)Abstract:

PURPOSE: To rationalize a manufacturing process, and to reduce manufacturing cost by improving the arrangement of printed wiring boards regarding a multiple beveled substrate, in which a large number of the printed wiring boards are arranged on one substrate.

CONSTITUTION: Mutually the same electronic components are mounted on the mounting surfaces A of printed wiring boards 1, 2, and mutually the same components are also mounted similarly on mounting surfaces B. These printed wiring boards 1, 2 are linearly symmetrized centering around symmetry axes 3 on substrates 5, and arranged so that the mounting surfaces A, B are positioned on the surfaces and rears of the substrates 5 respectively. When the substrates are reversed centering around the symmetry axes 3, the mounting surfaces, on which the same electronic components are mounted, in the opposed printed wiring boards are positioned.



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